MULTI-STEP PLANARIZING AND POLISHING METHOD

ABSTRACT OF THE DISCLOSURE

A multi-step planarizing and polishing method includes performing a first and a second polishing steps, wherein one of the two polishing steps is performed using a silica abrasive based slurry, while the other one of the two polishing steps is performed using a CeO_2 abrasive based slurry. A third polishing step is further performed using a fixed abrasive pad. Further, the thickness deviation of wafers entering the third polishing step is controlled.

Figure 2.